

DESCRIPTION

The PESD5V0S1UL,315-JSM is designed to protect voltage sensitive components from ESD and transient voltage events. Excellent clamping capability, low leakage, and fast response time, make these parts ideal for ESD protection on designs where board space is at a premium. Because of its small size, it is suited for use in cellular phones, portable devices, digital cameras, power supplies and many other portable applications.



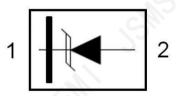
- ◆ Transient protection for high-speed data lines IEC 61000-4-2 (ESD) ±15kV (Air) ±8kV (Contact)
- ◆ Protects one directional I/O line
- ◆Low clamping voltage
- ♦ Working voltages: 3.3V, 5V, 8V, 12V, 15V
- ◆ Low leakage current

APPLICATIONS

- ◆Cell Phone Handsets and Accessories
- Microprocessor based equipment
- ◆Personal Digital Assistants (PDA's)
- ♦ Notebooks, Desktops, and Servers
- ◆Portable Instrumentation
- ◆Peripherals
- ◆Pagers



PACKAGE OUTLINE



PIN CONFIGURATION

MACHANICAL DATA

◆DFN1006 package

◆Packaging: Tape and Reel

◆High temperature soldering guaranted: 260°C/10s

◆Reel size: 7 inch



ABSOLUTE MAXIMUM RATING

Symbol	Parameter	Value	Units	
\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	ESD per IEC 61000-4-2 (Air)	±30	C.	
V_{ESD}	ESD per IEC 61000-4-2 (Contact)	±22	Kv	
P_D	Total Power Dissipation on FR-5 Board (Note 1) @ Ta=25°C	150	Mw	
$T_{J_{i}}T_{STG}$	Junction and Storage Temperature	-55/+150	°C	
TL	Lead Solder Temperature – Maximum (10 Second Duration)	260	°C	

These ratings are limiting values above which the serviceability of the diode may be impaired Note 1. FR-5=1.0x0.75x0.62 in.

ELECTRICAL CHARACTERISTICS (Tamb=25°C)

Part Number	V _{RWM} (V) Max.	I _R (μΑ) Max.	V _B (V) Min.	l _⊤ (Ma)		/c /) @A		/c /) @A)	(VV) Ppk Max.	C _J (Pf)Max.
PESD5V0S1UL,315- JSM	5.0	1	6.2	1	11.6	5.0	15.0	7.0	105	80

ELECTRICAL CHARACTERISTICS CURVE

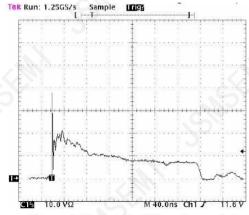
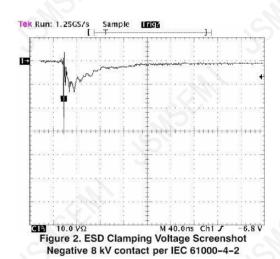
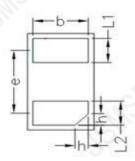


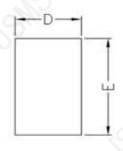
Figure 1. ESD Clamping Voltage Screenshot Positive 8 kV contact per IEC 61000-4-2





DFN1006 PACKAGE OUTLINE DIMENSIONS



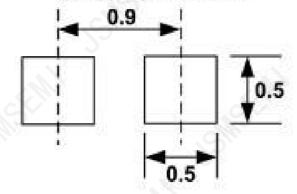




Unit: mm

	MIN	NOM	MAX		
D	0.55	0.60	0.65		
E	0.95	1.00	1.05		
L1	0.20	0.25	0.30		
L2	0.20	0.25	0.30		
ь	0.45	0.50	0.55		
е	0.65BSC				
Α	0.45	0.50	0.55		
h	0.07	0.12	0.17		

Dimension: Millimeter (Stencil thickness: 0.1)



Soldering Footprint



Revision History

Rev.	Change	Date
V1.0	Initial version	2/23/2024

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